

RH850 FAMILY GEN1 PRODUCT PART NUMBER

2/APRIL/2026
RENESAS ELECTRONICS CORPORATION
REV 1.00

F1KX MATERIAL CODE NOMENCLATURE

Material/ Version

R7 F 70 10 35 3 A FP -C #YJ1

MCU

R	Renesas
7	MCU (high)
F	Flash
70	RH850

Series

10	F1L
15	F1M, F1H, F1K
16	F1K, F1KM-S1, F1KM-S1 HT, F1KM-S4
17	F1KM-S2, F1KH-D8
1A	F1KM-S4, S2 High Temp.

Device

xx	Device specific number
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Temperature

3	Ta = -40 to + 105°C
4	Ta = -40 to + 125°C
F	Tj = -40 to + 160°C

A	Automotive
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Packaging	
#Axx	Tray (Now, non-promotion)
#Bxx	Tray (Full carton)
#Kxx	T&R QFP (top right, formerly -E3)
#Txx	T&R QFP (top right, formerly -E3, increasing storage capacity)
#Lxx	T&R BGA (top left, formerly -E2)
Plating	
#xAx	Pb free/ Sn plating
#xCx	Pb free/
Sample Versions	
#Yxx	Sample
#YJx	WS = Working Sample
#YKx	ES = Engineering Sample
#YBx	CS = Commercial Sample
Product Version	
#xxx	x = 1, 2, 3,....

Bonding

-C	Cu wire bonding
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*no indication for Au wire

Package

FP	LQFP (ASSY=RSC)
FD	LQFP (ASSY=ATJ-Kumamoto)
FE	LQFP (ASSY=ASE-KH)
BG	BGA (ASSY=Yonezawa)
BE	BGA (ASSY=ASE-KH)

Please note that the above information may be changed without advance notice.

P1X MATERIAL CODE NOMENCLATURE

R7 F 70 13 00 E A FP -C #YJ1

MCU

R	Renesas
7	MCU (high)
F	Flash
70	RH850

Series

13	P1x : Chassis / Safety
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Device

0x-2x	P1M
6x	P1M
75-86	P1M-E
70	P1H-CE
71,72,96	P1H-C
73,74,97	P1M-C
88-91	P1L-C

Temperature

E	Tj = -40 to + 150°C
G	Tj = -40 to + 160°C

A	Automotive
E	Emulation Device

Material/ Version	
Packaging	
#Axx	Tray
#Bxx	Tray (Full carton)
#Kxx	T&R QFP (top right, formerly -E3)
#Lxx	T&R BGA (top left, formerly -E2)
Plating	
#xAx	Pb free/ Sn plating
#xCx	Pb free/
Sample Versions	
#Yxx	Sample
#YJx	WS = Working Sample
#YKx	ES = Engineering Sample
#YBx	CS = Commercial Sample
Product Version	
#xxx	x = 1, 2, 3,....

Bonding

-C	Cu wire bonding
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*no indication for Au wire

Package

FP	QFP
FA	QFP
BG	BGA

D1X MATERIAL CODE NOMENCLATURE

R7 F 70 14 17 E A FB -C #YJ1

MCU

R	Renesas
7	MCU (high)
F	Flash
70	RH850

Series

14	D1
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Device

xx	Device specific number
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Temperature

E	Tj = -40 to + 150°C
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A	Automotive
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Material/ Version	
Packaging	
#Axx	Tray (Now, non-promotion)
#Bxx	Tray (Full carton)
#Kxx	T&R QFP (top right, formerly -E3)
#Txx	T&R QFP (top right, formerly -E3, increasing storage capacity)
#Lxx	T&R BGA (top left, formerly -E2)
Plating	
#xAx	Pb free/ Sn plating
#xCx	Pb free/
Sample Versions	
#Yxx	Sample
#YJx	WS = Working Sample
#YKx	ES = Engineering Sample
#YBx	CS = Commercial Sample
Product Version	
#xxx	x = 1, 2, 3,....
Bonding	
-C	Cu wire bonding
	*no indication for Au wire
Package	
FB	LQFP
FD	LQFP
FE	LQFP
BG	BGA

Please note that the above information may be changed without advance notice.

C1X/C1M-AX MATERIAL CODE NOMENCLATURE

R7 F 70 12 78 E A FP -C #YJ1

MCU

R	Renesas
7	MCU (high)
F	Flash
70	RH850

Series

12	C1x, C1M-Ax : Powertrain
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Device

xx	Device specific number
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Temperature

E	Tj = -40 to + 150°C
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A	Automotive
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Material/ Version	
	Packaging
#Axx	Tray
#Bxx	Tray (Full carton)
#Hxx	T&R BGA (top left, formerly -E2)
	Plating
#xAx	Pb free/ Sn plating
#xCx	Pb free/
	Sample Versions
#Yxx	Sample
#YJx	WS = Working Sample
#YKx	ES = Engineering Sample
#YBx	CS = Commercial Sample
	Product Version
#xxx	x = 0, 1, 2, 3,....

Bonding

-C	Cu wire bonding
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*no indication for Au wire

Package

FP	LQFP
BG	BGA

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E1X MATERIAL CODE NOMENCLATURE

R7 F 70 12 * * E A FP -C #YJ1

MCU

R	Renesas
7	MCU (high)
F	Flash
70	RH850

Series

12	E1x : Powertrain
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Device

xx	Device specific number
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Temperature

E	Tj = -40 to + 150°C
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A	Automotive
---	------------

Material/ Version	
Packaging	
#Axx	Tray
#Bxx	Tray (Full carton)
#Kxx	T&R QFP (top right, formerly -E3)
#Lxx	T&R BGA (top left, formerly -E2)
Plating	
#xAx	Pb free/ Sn plating
#xCx	Pb free/
Sample Versions	
#Yxx	Sample
#YJx	WS = Working Sample
#YKx	ES = Engineering Sample
#YBx	CS = Commercial Sample
Product Version	
#xxx	x = 0, 1, 2, 3,....

Bonding

-C	Cu wire bonding
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*no indication for Au wire

Package

FA	QFP144
FP	QFP176
BA	BGA252
BG	BGA304

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